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Product Information Notification

Product Group: TC/Tuesday September 9, 2025/PIN-TC-010-2025-REV-0



Update moisture sensitivity label with 24 months calculated shelf life

For further information, please contact your regional Vishay office.

CONTACT INFORMATION

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Description of Change: Added 24 months calculated shelf life at <30C and <70% Related humidity.

Vishay reserves the right to use both label styles.

Reason for Change: Moisture sensitivity label update.

Expected Influence on Quality/Reliability/Performance: No.

Part Numbers/Series/Families Affected: Please see materials list on the succeeding page.

Vishay Brand(S): Vishay

Time Schedule:

Start Shipment Date: Thursday October 9, 2025

Sample Availability: Upon Request.

Product Identification: N/A

Qualification Data: N/A

Issued By:



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T52*	T54*	T55*	T56*	T58*
T59*	04051*	20021*		

**Polymer products (LEAD(Pb)-Free)
T52, T55, T58, T56 (Cases "B" and "V")**

Current MSL label PEAK PACKAGE BODY TEMPERATURE (TP) MAX.260°C	New MSL label (change marked Yellow) PEAK PACKAGE BODY TEMPERATURE (TP) MAX.260°C
 CAUTION Level (MSL) 3 This bag contains MOISTURE – SENSITIVE DEVICES AND PROCESS SENSITIVE DEVICES 1. Calculated shelf life in sealed bag: 12 months at < 40°C and < 90% relative humidity (RH) Bag Seal Date: _____ 2. Peak package body temperature 260°C 3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be a) Mounted within: 168 hours of factory conditions < 30°C/60% RH, or b) Stored per J – STD – 033 4. Devices require bake, before mounting, if: a) Humidity Indicator Card reads > 10% for level 2a – 5a devices or > 60% for level 2 devices when read at 23 ± 5°C b) 3a or 3b are not met 5. If baking is required, refer to IPC/JEDEC J – STD – 033 for bake procedure Note1: Level (MSL) and body temperature defined by IPC/JEDEC J – STD – 020 Note2: Process Sensitivity Levels (PCLs) defined by ECIA/IPC/JEDEC J – STD – 075 PROCESS SENSITIVE DEVICES Level (PSL) R4G PSL Additional Information: Time(tp) is 5 seconds Form# 150192	 CAUTION Level (MSL) 3 This bag contains MOISTURE – SENSITIVE DEVICES AND PROCESS SENSITIVE DEVICES 1. Calculated shelf life in sealed bag: a) 12 months at < 40°C and < 90% relative humidity (RH) b) 24 months at < 30°C and < 70% relative humidity (RH) Bag Seal Date: _____ 2. Peak package body temperature 260°C 3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be a) Mounted within: of factory conditions < 30°C/60% RH, or b) Stored per J – STD – 033 4. Devices required bake, before mounting, if: a) Humidity Indicator Card reads > 10% for level 2a – 5a devices or > 60% for level 2 devices when read at 23 ± 5°C b) 3a or 3b are not met 5. If baking is required, refer to IPC/JEDEC J – STD – 033 for bake procedure Note1: Level (MSL) and body temperature defined by IPC/JEDEC J – STD – 020 Note2: Process Sensitivity Levels (PCLs) defined by ECIA/IPC/JEDEC J – STD – 075 PROCESS SENSITIVE DEVICES Level (PSL) R4G PSL Additional Information: Time(tp) is 5 seconds Form# 150192 – 1

**Polymer products (LEAD(Pb)-Free)
T59, T54, T56 (Case "D")**

Current MSL label PEAK PACKAGE BODY TEMPERATURE (TP) MAX.250°C	New MSL label (change marked Yellow) PEAK PACKAGE BODY TEMPERATURE (TP) MAX.250°C
 CAUTION Level (MSL) 3 This bag contains MOISTURE – SENSITIVE DEVICES AND PROCESS SENSITIVE DEVICES 1. Calculated shelf life in sealed bag: 12 months at < 40°C and < 90% relative humidity (RH) Bag Seal Date: _____ 2. Peak package body temperature 250°C 3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be a) Mounted within: 168 hours of factory conditions < 30°C/60% RH, or b) Stored per J – STD – 033 4. Devices require bake, before mounting, if: a) Humidity Indicator Card reads > 10% for level 2a – 5a devices or > 60% for level 2 devices when read at 23 ± 5°C b) 3a or 3b are not met 5. If baking is required, refer to IPC/JEDEC J – STD – 033 for bake procedure Note1: Level (MSL) and body temperature defined by IPC/JEDEC J – STD – 020 Note2: Process Sensitivity Levels (PCLs) defined by ECIA/IPC/JEDEC J – STD – 075 PROCESS SENSITIVE DEVICES Level (PSL) R6G PSL Additional Information: Time(tp) is 5 seconds Form# 150192	 CAUTION Level (MSL) 3 This bag contains MOISTURE – SENSITIVE DEVICES AND PROCESS SENSITIVE DEVICES 1. Calculated shelf life in sealed bag: a) 12 months at < 40°C and < 90% relative humidity (RH) b) 24 months at < 30°C and < 70% relative humidity (RH) Bag Seal Date: _____ 2. Peak package body temperature 250°C 3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be a) Mounted within: of factory conditions < 30°C/60% RH, or b) Stored per J – STD – 033 4. Devices required bake, before mounting, if: a) Humidity Indicator Card reads > 10% for level 2a – 5a devices or > 60% for level 2 devices when read at 23 ± 5°C b) 3a or 3b are not met 5. If baking is required, refer to IPC/JEDEC J – STD – 033 for bake procedure Note1: Level (MSL) and body temperature defined by IPC/JEDEC J – STD – 020 Note2: Process Sensitivity Levels (PCLs) defined by ECIA/IPC/JEDEC J – STD – 075 PROCESS SENSITIVE DEVICES Level (PSL) R6G PSL Additional Information: Time(tp) is 5 seconds Form# 150192 – 1

Polymer products (Sn / Pb solder)

T59, T54, 20021, 04051 (Case "D")

Current MSL label PEAK PACKAGE BODY TEMPERATURE (TP) MAX.220°C	New MSL label (change marked Yellow) PEAK PACKAGE BODY TEMPERATURE (TP) MAX.220°C
 CAUTION Level (MSL) 3 This bag contains MOISTURE – SENSITIVE DEVICES 1. Calculated shelf life in sealed bag: 12 months at < 40°C and < 90% relative humidity (RH) Bag Seal Date: _____ 2. Peak package body temperature 220°C 3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be a) Mounted within: 168 hours of factory conditions < 30°C/60% RH, or b) Stored per J – STD – 033 4. Devices required bake, before mounting, if: a) Humidity Indicator Card reads > 10% for level 2a – 5a devices or > 60% for level 2 devices when read at 23 ± 5°C b) 3a or 3b are not met 5. If baking is required, refer to IPC/JEDEC J – STD – 033 for bake procedure Note 1: Level (MSL) and body temperature defined by IPC/JEDEC J – STD – 020 Form# 150194	 CAUTION Level (MSL) 3 This bag contains MOISTURE – SENSITIVE DEVICES 1. Calculated shelf life in sealed bag: a) 12 months at < 40°C and < 90% relative humidity (RH) b) 24 months at < 30°C and < 70% relative humidity (RH) Bag Seal Date: _____ 2. Peak package body temperature 220°C 3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be a) Mounted within: of factory conditions < 30°C/60% RH, or b) Stored per J – STD – 033 4. Devices required bake, before mounting, if: a) Humidity Indicator Card reads > 10% for level 2a – 5a devices or > 60% for level 2 devices when read at 23 ± 5°C b) 3a or 3b are not met 5. If baking is required, refer to IPC/JEDEC J – STD – 033 for bake procedure Note 1: Level (MSL) and body temperature defined by IPC/JEDEC J – STD – 020 Form# 150194 – 1

Polymer products (Sn / Pb solder)

(04051, Case "B")

Current MSL label PEAK PACKAGE BODY TEMPERATURE (TP) MAX.235°C	New MSL label (change marked Yellow) PEAK PACKAGE BODY TEMPERATURE (TP) MAX.235°C
 CAUTION Level (MSL) 3 This bag contains MOISTURE – SENSITIVE DEVICES 1. Calculated shelf life in sealed bag: 12 months at < 40°C and < 90% relative humidity (RH) Bag Seal Date: _____ 2. Peak package body temperature 235°C 3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be a) Mounted within: 168 hours of factory conditions < 30°C/60% RH, or b) Stored per J – STD – 033 4. Devices required bake, before mounting, if: a) Humidity Indicator Card reads > 10% for level 2a – 5a devices or > 60% for level 2 devices when read at 23 ± 5°C b) 3a or 3b are not met 5. If baking is required, refer to IPC/JEDEC J – STD – 033 for bake procedure Note 1: Level (MSL) and body temperature defined by IPC/JEDEC J – STD – 020 Form# 150194	 CAUTION Level (MSL) 3 This bag contains MOISTURE – SENSITIVE DEVICES 1. Calculated shelf life in sealed bag: a) 12 months at < 40°C and < 90% relative humidity (RH) b) 24 months at < 30°C and < 70% relative humidity (RH) Bag Seal Date: _____ 2. Peak package body temperature 235°C 3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be a) Mounted within: 168 hours of factory conditions < 30°C/60% RH, or b) Stored per J – STD – 033 4. Devices required bake, before mounting, if: a) Humidity Indicator Card reads > 10% for level 2a – 5a devices or > 60% for level 2 devices when read at 23 ± 5°C b) 3a or 3b are not met 5. If baking is required, refer to IPC/JEDEC J – STD – 033 for bake procedure Note 1: Level (MSL) and body temperature defined by IPC/JEDEC J – STD – 020 Form# 150194 – 1